Dual NPN Bias Resistor Transistors

R1 = 10 k Ω , R2 = 47 k Ω

NPN Transistors with Monolithic Bias Resistor Network

MUN5214DW1, NSBC114YDXV6, NSBC114YDP6

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

(T_A = 25°C, common for Q₁ and Q₂, unless otherwise noted)

Rating	Symbol	Max	Unit
Collector-Base Voltage	V_{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current - Continuous	Ic	100	mAdc
Input Forward Voltage	$V_{IN(fwd)}$	40	Vdc
Input Reverse Voltage	V _{IN(rev)}	6	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

Device	Package	Shipping [†]
MUN5214DW1T1G, SMUN5214DW1T1G*, NSVMUN5214DW1T2G*	SOT-363	3,000 / Tape & Reel
NSVMUN5214DW1T3G*	SOT-363	10,000 / Tape & Reel
NSBC114YDXV6T1G NSVBC114YDXV6T1G*	SOT-563	4,000 / Tape & Reel
NSBC114YDXV6T5G	SOT-563	8,000 / Tape & Reel
NSBC114YDP6T5G	SOT-963	8,000 / Tape & Reel

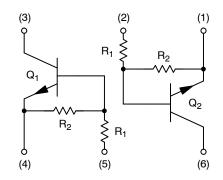
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



ON Semiconductor®

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PIN CONNECTIONS



MARKING DIAGRAMS



SOT-363 CASE 419B





SOT-563 CASE 463A





SOT-963 CASE 527AD



7D/P = Specific Device Code

M = Date Code*
■ Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

THERMAL CHARACTERISTICS

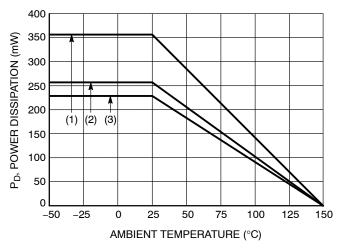
	Characteristic	Symbol	Max	Unit
MUN5214DW1 (SOT-363) ON	IE JUNCTION HEATED			
Total Device Dissipation $T_A = 25^{\circ}C \qquad \text{(Note 1)}$ (Note 2) Derate above 25°C (Note 2)	(Note 1)	P _D	187 256 1.5 2.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1) (Note 2)	$R_{ heta JA}$	670 490	°C/W
MUN5214DW1 (SOT-363) BC	OTH JUNCTION HEATED (Note 3)	<u>.</u>		
Total Device Dissipation $T_A = 25^{\circ}C \qquad \text{(Note 1)}$ (Note 2) Derate above 25°C (Note 2)	(Note 1)	P _D	250 385 2.0 3.0	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 2)	(Note 1)	$R_{ hetaJA}$	493 325	°C/W
Thermal Resistance, Junction to Lead (Note 1) (Note 2)		$R_{ heta JL}$	188 208	°C/W
Junction and Storage Temper	ature Range	T _J , T _{stg}	-55 to +150	°C
NSBC114YDXV6 (SOT-563)	ONE JUNCTION HEATED			
Total Device Dissipation T _A = 25°C (Note 1) Derate above 25°C	(Note 1)	P _D	357 2.9	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ heta JA}$	350	°C/W
NSBC114YDXV6 (SOT-563)	BOTH JUNCTION HEATED (Note 3)			
Total Device Dissipation $T_A = 25^{\circ}C$ (Note 1) Derate above 25°C	(Note 1)	P _D	500 4.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ heta JA}$	250	°C/W
Junction and Storage Temper	ature Range	T _J , T _{stg}	-55 to +150	°C
NSBC114YDP6 (SOT-963) O	NE JUNCTION HEATED			
Total Device Dissipation T _A = 25°C (Note 4) (Note 5) Derate above 25°C (Note 5)	(Note 4)	P _D	231 269 1.9 2.2	MW mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	(Note 4)	$R_{ hetaJA}$	540 464	°C/W
NSBC114YDP6 (SOT-963) B	OTH JUNCTION HEATED (Note 3)	·		
Total Device Dissipation T _A = 25°C (Note 4) (Note 5) Derate above 25°C (Note 5)	(Note 4)	P _D	339 408 2.7 3.3	MW mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	(Note 4)	$R_{ hetaJA}$	369 306	°C/W
Junction and Storage Temper	ature Range	T _J , T _{stg}	-55 to +150	°C

- FR-4 @ Minimum Pad.
 FR-4 @ 1.0 × 1.0 Inch Pad.
 Both junction heated values assume total power is sum of two equally powered channels.
 FR-4 @ 100 mm², 1 oz. copper traces, still air.
 FR-4 @ 500 mm², 1 oz. copper traces, still air.

ELECTRICAL CHARACTERISTICS (T_A = 25°C, common for Q₁ and Q₂, unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			1	1	•
Collector-Base Cutoff Current $(V_{CB} = 50 \text{ V}, I_E = 0)$	Ісво	-	-	100	nAdc
Collector-Emitter Cutoff Current (V _{CE} = 50 V, I _B = 0)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current (V _{EB} = 6.0 V, I _C = 0)	I _{EBO}	-	-	0.2	mAdc
Collector-Base Breakdown Voltage (I _C = 10 μA, I _E = 0)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage (Note 6) (I _C = 2.0 mA, I _B = 0)	V _{(BR)CEO}	50	-	-	Vdc
ON CHARACTERISTICS					
DC Current Gain (Note 6) (I _C = 5.0 mA, V _{CE} = 10 V)	h _{FE}	80	140	-	
Collector-Emitter Saturation Voltage (Note 6) $(I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA})$	V _{CE(sat)}	-	-	0.25	V
Input Voltage (Off) ($V_{CE} = 5.0 \text{ V}, I_C = 100 \mu\text{A}$)	V _{i(off)}	-	0.7	0.3	Vdc
Input Voltage (On) ($V_{CE} = 0.2 \text{ V}, I_C = 1.0 \text{ mA}$)	V _{i(on)}	1.4	0.8	-	Vdc
Output Voltage (On) ($V_{CC} = 5.0 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1.0 \text{ k}\Omega$)	V _{OL}	-	-	0.2	Vdc
Output Voltage (Off) (V _{CC} = 5.0 V, V _B = 0.5 V, R _L = 1.0 k Ω)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	7	10	13	kΩ
Resistor Ratio	R ₁ /R ₂	0.17	0.21	0.25	

^{6.} Pulsed Condition: Pulse Width = 300 ms, Duty Cycle ≤ 2%.



(1) SOT-363; 1.0×1.0 Inch Pad

Figure 1. Derating Curve

⁽²⁾ SOT-563; Minimum Pad

⁽³⁾ SOT-963; 100 mm², 1 oz. Copper Trace

TYPICAL CHARACTERISTICS MUN5214DW1, NSBC114YDXV6

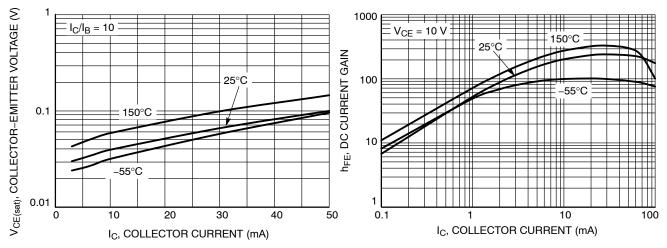


Figure 2. V_{CE(sat)} vs. I_C

Figure 3. DC Current Gain

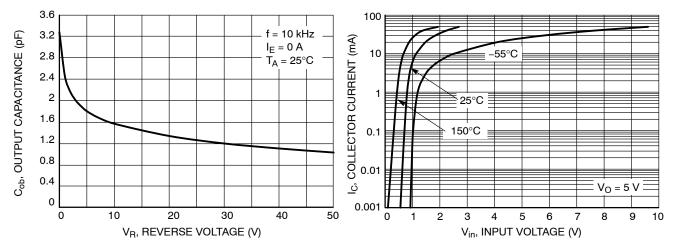


Figure 4. Output Capacitance

Figure 5. Output Current vs. Input Voltage

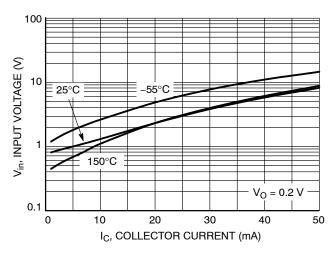


Figure 6. Input Voltage vs. Output Current

TYPICAL CHARACTERISTICS NSBC114YDP6

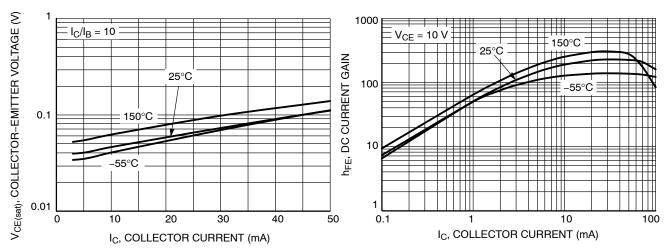


Figure 7. $V_{CE(sat)}$ vs. I_{C}

Figure 8. DC Current Gain

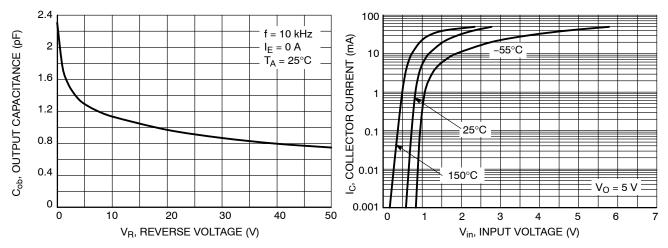


Figure 9. Output Capacitance

Figure 10. Output Current vs. Input Voltage

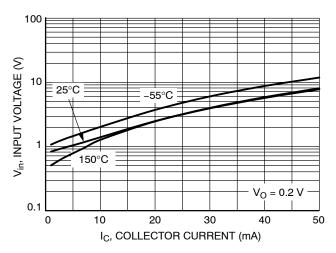


Figure 11. Input Voltage vs. Output Current





E1

e

В

SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 **ISSUE Z**

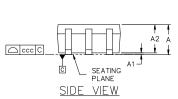
DATE 18 APR 2024

NOTES:

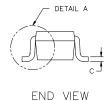
- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20
- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
- DIMENSIONS 6 AND C APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP. 6.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

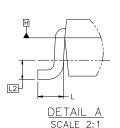
bbb

ccc ddd



TOP VIEW



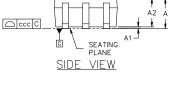


	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
Α			1.10	
A1	0.00		0.10	
A2	0.70	0.90	1.00	
b	0.15	0.20	0.25	
С	0.08	0.15	0.22	
D	2.00 BSC			
E	2.10 BSC			
E1	1.25 BSC			
е	0.65 BSC			
L	0.26	0.36	0.46	
L2	0.15 BSC			
aaa	0.15			

0.30

0.10

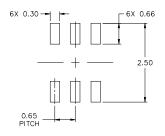
0.10



∆aaa H A−B

<u></u> БЬБ С

⊕ ddd M C A−B D



RECOMMENDED MOUNTING FOOTPRINT*

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

- *Date Code orientation and/or position may vary depending upon manufacturing location.
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.6	5P	PAGE 1 OF 2

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SC-88 2.00x1.25x0.90, 0.65P

CASE 419B-02 ISSUE Z

DATE 18 APR 2024

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P		PAGE 2 OF 2

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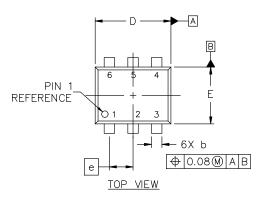


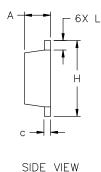
SOT-563-6 1.60x1.20x0.55, 0.50P CASE 463A ISSUE J

DATE 15 FEB 2024

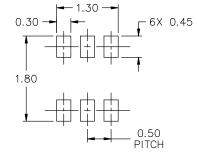
NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- 2. ALL DIMENSION ARE IN MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.





DIM	MILLIMETERS			
ויונע	MIN.	N□M.	MAX.	
А	0.50	0.55	0.60	
Ø	0.17	0.22	0.27	
C	0.08	0.13	0.18	
D	1.50	1.60	1.70	
E	1.10	1.20	1.30	
е	0.50 BSC			
Н	1.50	1.60	1.70	
L	0.10	0.20	0.30	



STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHODE 1
2. BASE 1	2. EMITTER 2	2. CATHODE 1
3. COLLECTOR 2	3. BASE 2	3. ANODE/ANODE 2
4. EMITTER 2	4. COLLECTOR 2	4. CATHODE 2
5. BASE 2	5. BASE 1	5. CATHODE 2
6. COLLECTOR 1	6. COLLECTOR 1	6. AN□DE/AN□DE 1

RECOMMENDED	MOLINITING	FOOTPRINT*
KECOMIMENDED	MOONTING	LOO INKINI.

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SDURCE 5. DRAIN 6. DRAIN	STYLE 9: PIN 1. SUURCE 1 2. GATE 1 3. DRAIN 2 4. SUURCE 2 5. GATE 2 6. DRAIN 1
6. CATHODE	6. DRAIN	6. DRAIN 1

PIN 1. EMITTER 2 2. BASE 2

COLLECTOR 1

EMITTER 1

STYLE 11:

2. 3.

STYLE 5:

PIN 1. CATHODE

2. CATHODE
3. ANODE
4. ANODE
5. CATHODE

GENERIC MARKING DIAGRAM*



XX = Specific Device CodeM = Month Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may

5. N/C
6. ANDE 1
6. COLLECTER 2

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STYLE 6: PIN 1. CATHODE 2. ANODE

3. CATHODE

4. CATHODE 5. CATHODE

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DESCRIPTION: SOT-563-6 1.60x1.20x0.55, 0.50P PAGE 1 OF 1

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STYLE 4: PIN 1. COLLECTOR

> 3. BASE 4. EMITTER 5. COLLECTOR

STYLE 10:

PIN 1. CATHODE 1 2. N/C 3. CATHODE 2

4. ANDDE 2

2. COLLECTOR

COLLECTOR





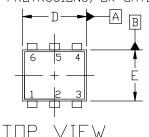
SOT-963 1.00x1.00x0.37, 0.35P CASE 527AD **ISSUE F**

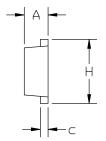
DATE 20 FEB 2024

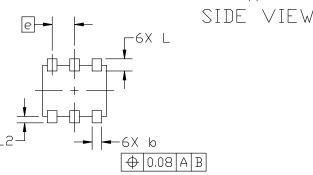
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018. 1.
- CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

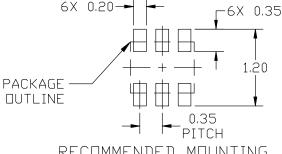
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS.







MILLIMETERS DIM MIN. $N\square M$. MAX. 0.37 0.40 Α 0.34 0.10 0.15 0.20 h \subset 0.07 0.12 0.17 D 0.95 1.00 1.05 Ε 0.75 0.80 0.85 0.35 BSC 6 Н 1.00 0.95 1.05 0.19 REF L2 0.05 0.10 0.15



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the $\square N$ Semiconductor Soldering and Mounting Techniques Reference manual, SDLDERRM/D.

BUTTUM VIEW

STYLE 1:	STY
PIN 1. EMITTER 1	PIN
2. BASE 1	
COLLECTOR 2	
4. EMITTER 2	
5. BASE 2	
COLLECTOR 1	
STYLE 4:	STY

PIN 1. COLLECTOR 2. COLLECTOR

3. BASE 4. EMITTER

STYLE 10: PIN 1. CATHODE 1

2. N/C 3. CATHODE 2

4. ANODE 2

5. N/C 6. ANODE 1

5 COLLECTOR

6. COLLECTOR

/LE 2:	
N 1. EMITTER 1	
2. EMITTER2	
3. BASE 2	
4. COLLECTOR 2	
5. BASE 1	
COLLECTOR 1	

STYLE 3:
PIN 1. CATHODE 1
CATHODE 1
ANODE/ANODE 2
4. CATHODE 2

5. CATHODE 2 6. ANODE/ANODE 1

STYLE 5: STYLE 6:

PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE CATHODE
 CATHODE

STYLE 7: PIN 1. CATHODE 2. ANODE

STYLE 8: PIN 1. DRAIN 2. DRAIN 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE 5. DRAIN 6. DRAIN

STYLE 9: PIN 1. SOURCE 1 2. GATE 1 3. GATE 4. SOURCE 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1

GENERIC MARKING DIAGRAM*



XX = Specific Device Code = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

DESCRIPTION:	SOT-963 1.00x1.00x0.37, 0.35P		PAGE 1 OF 1
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